查询"2SK23903供应商Field Effect Transistor Silicon N-Channel MOS Type (L<sup>2</sup>-π-MOSV)

# 2SK2399

Chopper Regulator, DC/DC Converter and Motor Drive Applications

- 4 V gate drive
- Low drain-source ON-resistance  $: R_{DS} (ON) = 0.17 \Omega (typ.)$
- High forward transfer admittance  $|Y_{fs}| = 4.5 \text{ S (typ.)}$
- Low leakage current  $: IDSS = 100 \ \mu A \ (max) \ (VDS = 100 \ V)$
- Enhancement mode  $: V_{th} = 0.8 \sim 2.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ ID} = 1 \text{ mA})$

#### Absolute Maximum Ratings (Ta = 25°C)

Character	istic	Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	100	V	
Drain-gate voltage (R	<sub>GS</sub> = 20 kΩ)	V <sub>DGR</sub>	100	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	5	А	
	Pulse (Note 1)	I <sub>DP</sub>	20	А	
Drain power dissipatio	n (Tc = 25°C)	PD	20	W	
Single-pulse avalanch	e energy (Note 2)	E <sub>AS</sub>	180	mJ	
Avalanche current		I <sub>AR</sub>	5	А	
Repetitive avalanche e	energy (Note 3)	E <sub>AR</sub>	2	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature r	ange	T <sub>stg</sub>	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

#### **Thermal Characteristics**

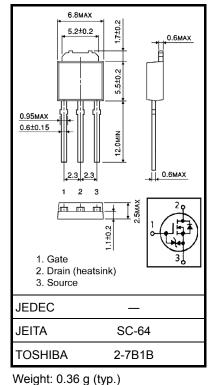
Characteristic	Symbol	Мах	Unit	
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	6.25	°C / W	
Thermal resistance, channel to ambient	R <sub>th (ch−a)</sub>	125	°C / W	

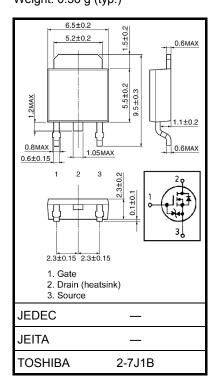
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD} = 25 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 11.6 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = 5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.





Weight: 0.36 g (typ.)

Unit: mm

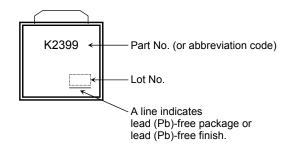
# Etectrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Мах	Unit	
Gate leakage current		I <sub>GSS</sub>	$V_{GS}$ = ±16 V, $V_{DS}$ = 0 V	_		±10	μA	
Drain cutoff curr	rent	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V		_	100	μA	
Drain-source bi	reakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V		_	_	V	
Gate threshold	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.8	_	2.0	V	
Drain-source ON-resistance		R <sub>DS (ON)</sub>	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 2.5 A	_	0.22	0.30	Ω	
			V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.5 A	_	0.17	0.23		
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	2.0	4.5	_	S	
Input capacitance Reverse transfer capacitance		C <sub>iss</sub>		_	500	_		
		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	80	_	pF	
Output capacitance		C <sub>oss</sub>	1	_	190			
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{}_{0V} \stackrel{I_{D}=2.5A}{}_{VOUT}$ $V_{GS} \stackrel{V_{OV}}{}_{0V} \stackrel{I_{D}=2.5A}{}_{VOUT}$ $R_{L}$ $= 20\Omega$ $V_{DD} = 50V$ $Duty \leq 1\%, t_{W} = 10\mu s$	_	17	_	ns	
	Turn-on time	t <sub>on</sub>		_	25	_		
	Fall time	tf		_	50	_		
	Turn-off time	t <sub>off</sub>		_	195	_		
Total gate charge (gate-source plus gate-drain)		Qg		_	22	_	nC	
Gate-source charge		Q <sub>gs</sub>	V <sub>DD</sub> ≈ 80 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5 A	_	15	_		
Gate-drain ("Miller") charge		Q <sub>gd</sub>	1		7	—	1	

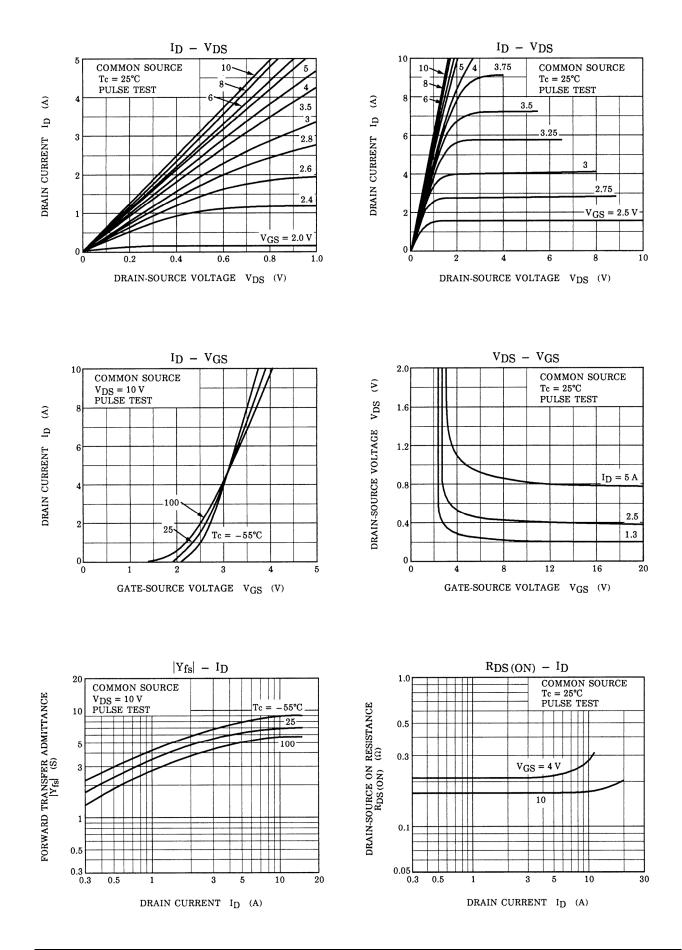
# Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	5	A
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	20	A
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V, dI <sub>DR</sub> / dt = 50 A / μs	_	160	_	ns
Reverse recovery charge	Q <sub>rr</sub>			0.28		μC

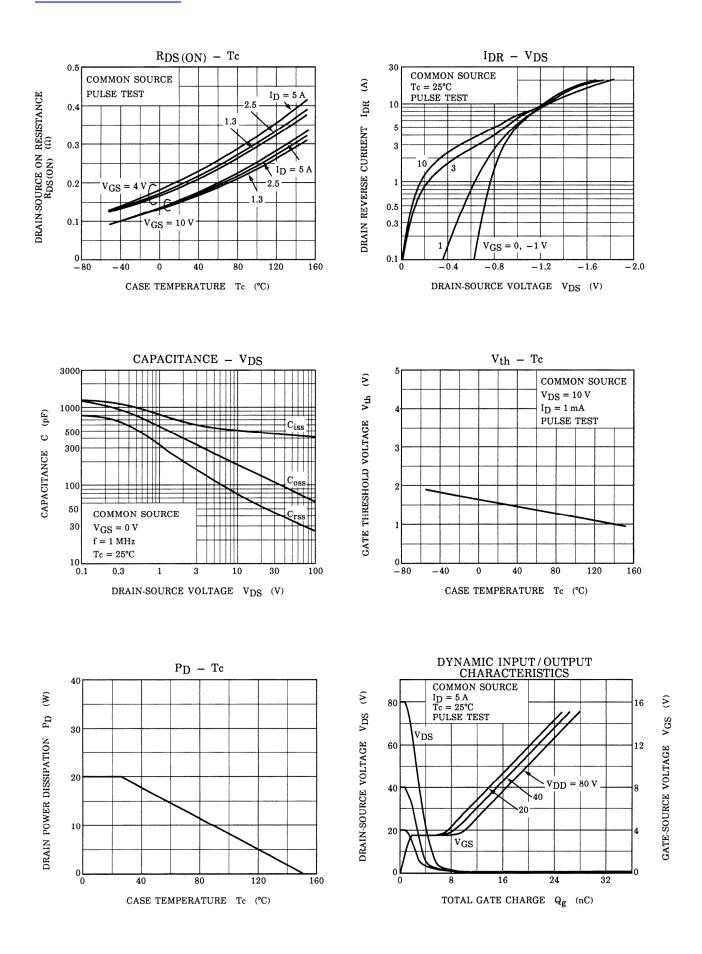
#### Marking



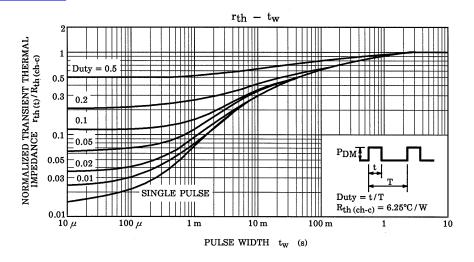
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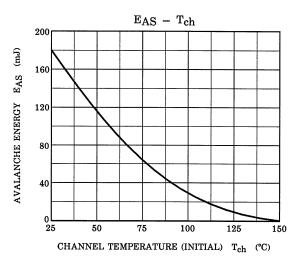


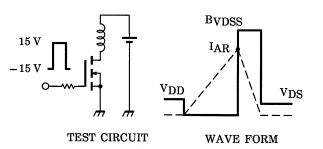
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SAFE OPERATING AREA 100 50 30  $I_D$  MAX. (PULSE)  $\times$ 100  $\mu$ s%Ð ID MAX. (PULSE) X ms× ď 10 ID MAX. (CONTINUOUS) DRAIN CURRENT |0 msЖ 5 3 DC OPERATION  $Tc = 25^{\circ}C$ 1 **% SINGLE NONREPETITIVE** 0.5  $PULSE \quad Tc = 25^{\circ}C$ 0.3 Curves must be derated linearly with increase in temperature. VDSS MAX 0.1L 0.3 1 3 10 30 100 300

DRAIN-SOURCE VOLTAGE  $V_{DS}$  (V)





 $\begin{array}{ll} R_G = 25 \ \Omega \\ V_{DD} = 25 \ V\!\!, \ L = 11.6 \ mH \end{array} & E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right) \end{array}$ 

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